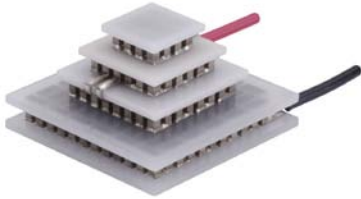


Multistage Series MS4-115-14-15-11

Thermoelectric Modules



The MS Series of thermoelectric modules (TEMs) are designed to reach cool down temperatures that are not achievable with single stage TEMs.

This product line is available in numerous heat pumping capacities, geometric shapes and temperature differentials. Assembled with Bismuth Telluride semiconductor material and thermally conductive Aluminum Oxide ceramics, the MS Series is designed for higher current and lower heat-pumping applications.

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Europe: +46.31.420530
Asia: +86.755.2714.1166
ets.sales@lairdtech.com
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FEATURES

- High temperature differential
- Precise temperature control
- Reliable solid state operation
- Environmentally friendly
- DC operation
- RoHS compliant

APPLICATIONS

- CCD cameras
- Electron microscope
- Calibration equipment
- Photonics laser systems
- Gas analyzers
- Infrared (IR) sensors
- Guidance systems

SPECIFICATIONS

TECHNICAL	
Hot Side Temperature (°C)	25°C
Qmax (Watts)	2.7
Delta Tmax (°C)	122
Imax (Amps)	3.5
Vmax (Volts)	7.5

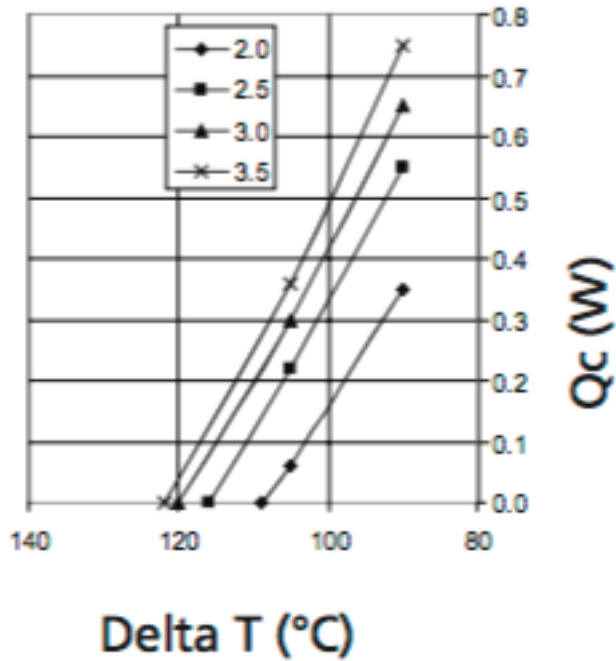
SUFFIX	THICKNESS (PRIOR TO TINNING)	FLATNESS & PARALLELISM	HOT FACE	COLD FACE	LEAD LENGTH
00	0.551"±0.008"	0.001"/0.004"	Metallized	Metallized	7.87"
11	0.543"±0.008"	0.001"/0.002"	Lapped	Lapped	7.87"
22	0.551"±0.008"	0.001"/0.004"	Pre-tinned	Pre-tinned	7.87"

SEALING OPTIONS

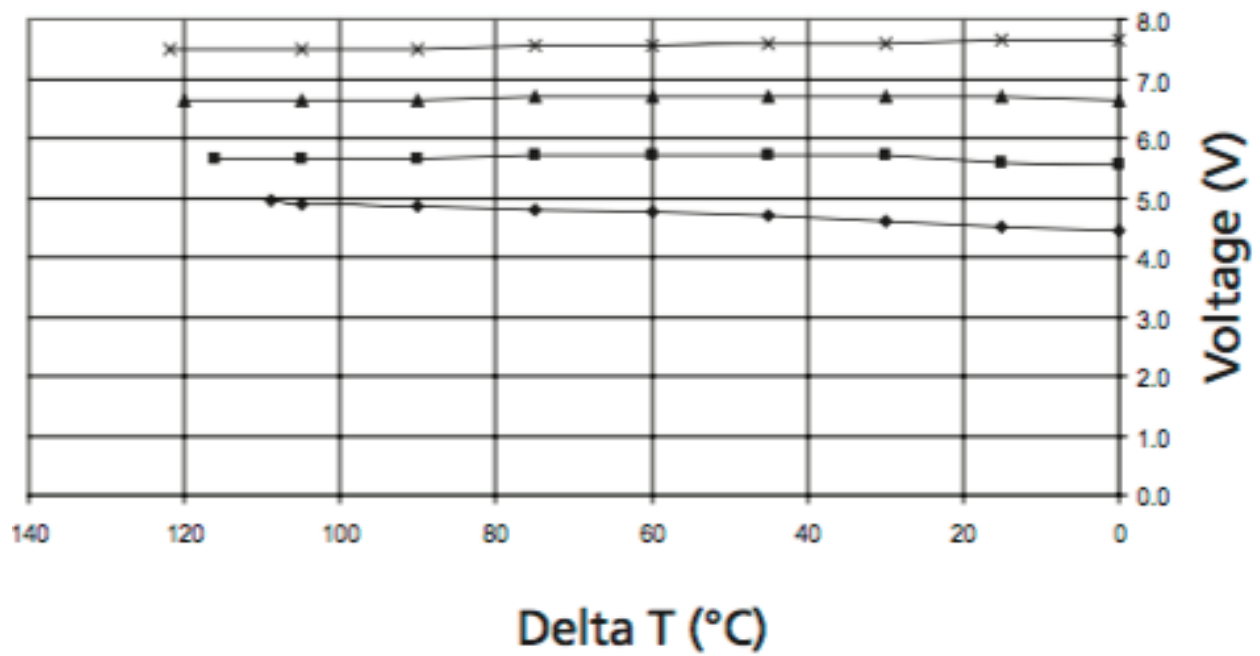
SUFFIX	SEALANT	COLOR	TEMP RANGE	DESCRIPTION
RT	RTV	White	-60 to 204 °C	Non-corrosive, silicone adhesive
EP	Epoxy	Black	-55 to 150 °C	Low density syntactic foam epoxy encapsulant

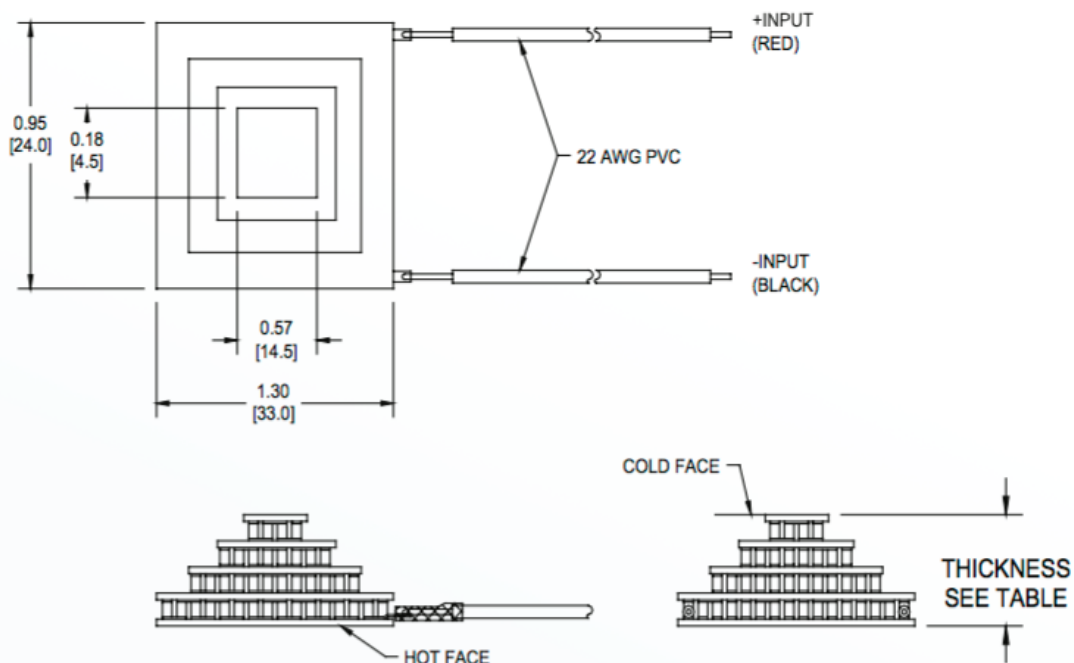
Performance Curves at $T_h = 25^\circ\text{C}$

THERMO



ELECTRIC





Ceramic Material: **Aluminum Nitride Ceramics**
Solder Construction: 138°C, Bismuth Tin (BiSn)

NOTES

1. Max operating temperature: 80°C
2. Do not exceed I_{max} or V_{max} when operating module
3. Reference assembly guidelines for recommended installation
4. Solder tinning also available on metallized ceramics

Laird-ETS-MS3-115-14-15-11-Data-Sheet-082216

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